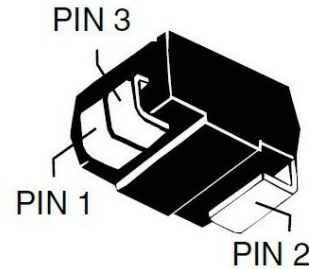


Features

- Bi-directional
- Excellent capability of absorbing transient surge
- Quick response to surge voltage (ns level)
- Eliminates overvoltage caused by fast rising transients
- Moisture sensitivity level: level 1
- Nondegenerative
- Weight 93mg

Dimensions SMB-3



Typical application including:

- Central office switching equipment. Analog and digital linecards (xDSL, T1/E1, ISDN.....)
- Customer Premises Equipment (CPE) such as phones, fax machines, modems, POS terminals, PBX systems and caller ID adjunct boxes.
- Primary protection modules including Main Distribution Frames (MDF), building entrance equipment and station protection modules.
- Access network equipment such as remote terminals, line repeaters, multiplexers, cross-connects, WAN equipment, Network Interface Devices (NID).
- Data lines and security systems.
- CATV line amplifiers and power inserters.
- Sprinkler systems.

Electrical Characteristics (Tamb=25°C)

Part Number	VDRM	IDRM	VBO	IBO	VT	IT	I _H	CO	IPP
	Min.	Max.	Max.	Max.	Max.	Max.	MAX.	Max.	Min.
	V	uA	V	mA	V	A	mA	pF	A
P0300-C2	25	5	40	800	4	2.2	55	100	100

General Notes:

All measurements are made at an ambient temperature of 25°C. Ipp applies to -40°C through +85°C temperature range.

Special voltage (VBO and VDRM) and holding current (I_H) requirements are available upon request.

Off-state capacitance (C₀) is measured at 1 MHz with a 2 V bias and is typical value.

Rating Surge Voltage: 100A(10/1000µs)

Electrical Parameters (Tamb=25°C)

Symbol	Parameter	Symbol	Parameter
V _{DRM}	Stand-off voltage, is measured at I _{DRM}	I _H	Holding current
I _{DRM}	Leakage current, is measured at V _{DRM}	I _T	ON-state current
V _{BO}	Breakover voltage, is measured at 100V/µs	V _T	On-state voltage
I _{BO}	Breadover current	C ₀	Off-state capacitance is measured in V _{DC} =2V@1MHz

Electrical Characteristics Curves

Figure1 V-I Characteristics

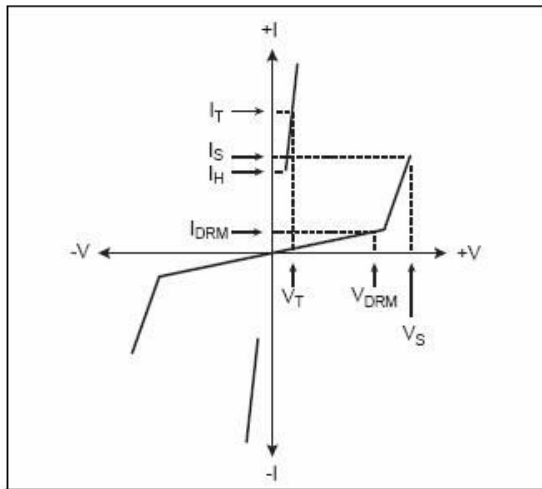


Figure2 tr x td Pulse Wave-form

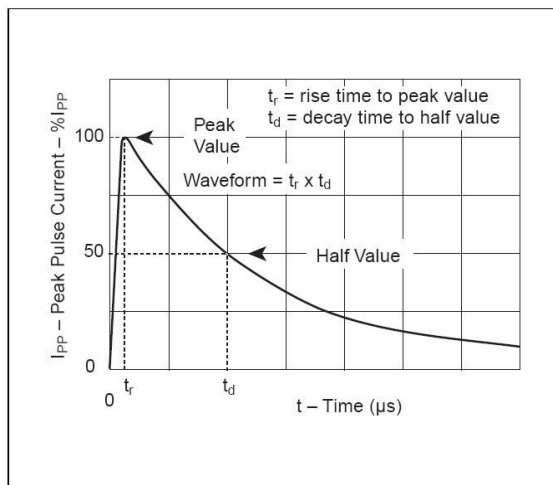
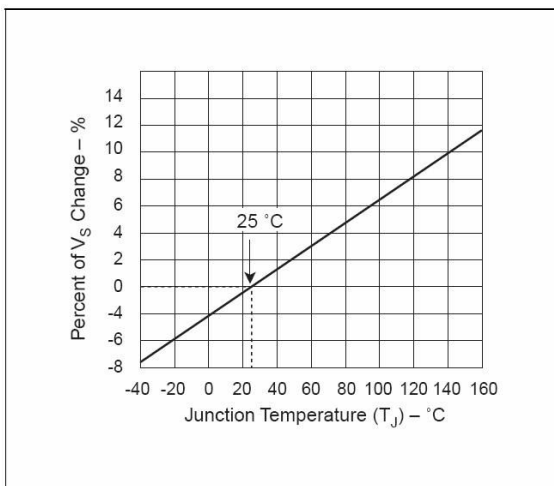
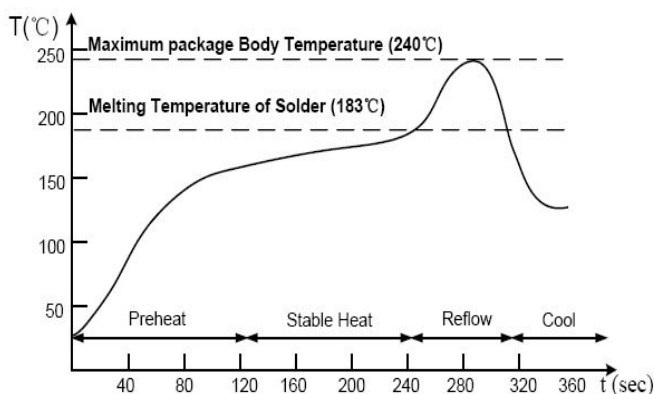


Figure 3 Normalized V_S Change versus Current



Solder Reflow Recommendations

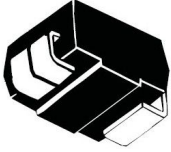


Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.

The device can be exposed to temperature of 265°C for 10 seconds. Devices can be cleaned using standard industry methods and solvents.

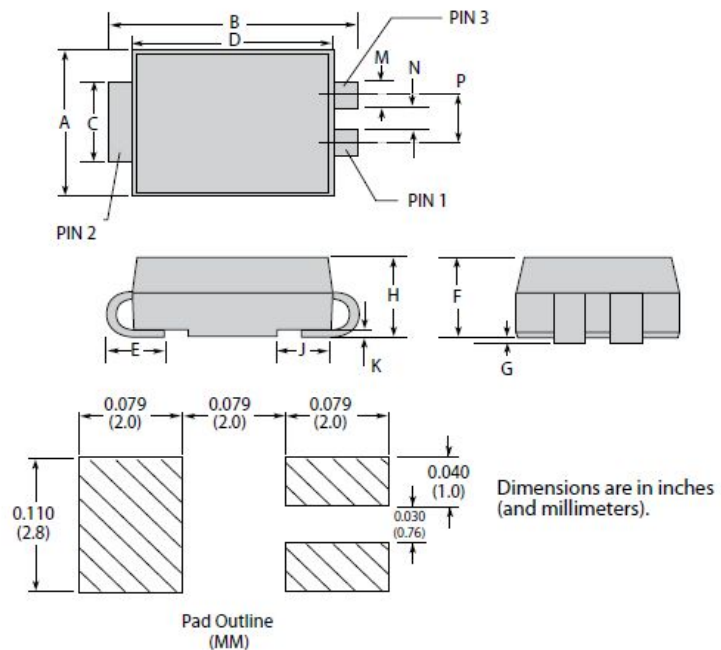
Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Thermal Considerations

Package SMB(DO-214AA)	Symbol	Parameter	Value	Unit
	T_J	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
	T_S	Storage Temperature Range	-40 to +150	$^{\circ}\text{C}$
	$R_{\theta JA}$	Junction to Ambient on printed circuit	90	$^{\circ}\text{C/W}$

Product Dimensions

Dimension	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.130	0.155	3.30	3.94
B	0.201	0.22	5.10	5.60
C	0.077	0.083	1.95	2.11
D	0.166	0.185	4.22	4.70
E	0.030	0.063	0.75	1.60
F	0.075	0.096	1.90	2.45
G	0.002	0.008	0.05	0.20
H	0.077	0.094	1.95	2.40
M	0.006	0.016	0.15	0.41
K	0.008	0.014	0.20	0.35
N	0.027	0.033	0.69	0.084
P	0.052	0.058	1.32	1.47



Summary of Packing Options

Package Type	Description	Packing Quantity	Industry Standard
DO-214AA(SMB-3)	Modified DO-214AA 3-leaded Tape Reel Pack	3000PCS	EIA-481-D

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